IPC ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type Distribute					rials and M	ials and Mfg Information				
Supplier	Information														
Company name*			Company unique ID			τ	Unique ID Authority				Respon	Response Date*			
nsemi											2024-05	2024-05-04			
Contact Na	ame		Title - Contact			1	Phone - Contact*				Email -	Email - Contact*			
Product-E	Env-Stewards		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized	d Representative*		Title - Representative			I	Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Da	te Version Manufacturing Site			Weight*	UOM	Unit Type		
		FDMS7658AS FET 30		FET 30V 1.9 mOhr	FET 30V 1.9 mOhm PQFN56		2024-05-04		•	CNJ		104.003	mg	Each	
Aanufa	cturing Proccess Informa	ation						·					·		
	Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MS	L Rating Peak Process Body Temperature Max Time at Pea				k Tempera	ture Numl	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU Alloy			1			260		C	30	seco	nds 3				
omments															
evel 1 - m	aximum time at peak temperat	ture during sol	dering is 10-3	0 seconds											
or more i	information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its keloardin shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.09	mg	Supplier	Silicon (Si)	7440-21-3		5.09	mg
Die Attach Solder	3.92	mg	Supplier	Silver (Ag)	7440-22-4		0.098	mg
			A	Lead (Pb)	7439-92-1	7a	3.626	mg
			Supplier	Tin (Sn)	7440-31-5		0.196	mg
Lead Frame	44.88		Supplier	Silver (Ag)	7440-22-4		0.1346	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0539	mg
			Supplier	Iron (Fe)	7439-89-6		1.0547	mg
			Supplier	Copper (Cu)	7440-50-8		43.6234	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0135	mg
Mold Compound-Black	47.25			Proprietary	proprietary data		3.78	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2362	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		43.2337	mg
Plating	0.445	mg	Supplier	Tin (Sn)	7440-31-5		0.445	mg
Wire Bond - Al	2.364	mg	Supplier	Aluminum (Al)	7429-90-5		2.364	mg
Wire Bond - Cu	0.054	mg	Supplier	Copper (Cu)	7440-50-8		0.054	mg